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8/30/02

PATENT APPLICATION  
Do. No. 9903-014

M. J. J. J.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Jong-Kon CHOI

Serial No. 09/847,620

Examiner: Mitchell, James M

Filed: May 2, 2001

Group Art Unit: 2827

For: METHOD FOR MANUFACTURING DIGITAL MICRO-MIRROR DEVICE  
(DMD) PACKAGES

BOX NON FEE AMENDMENT  
Assistant Commissioner for Patents  
Washington, D.C. 20231

RESPONSE TO OFFICE ACTION

Responsive to the Office Action, dated May 8, 2002, please amend the application as follows.

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IN THE CLAIMS

1. (Once amended) A method for manufacturing a semiconductor package, said method comprising:

A<sup>1</sup> providing a wafer including one or more semiconductor chips, each chip having one or more mirrors formed thereon and a plurality of bond pads formed on a periphery of the chip;

forming a photoresist over the one or more mirrors;

singulating the one or more semiconductor chips from the wafer;

mounting the one ore more semiconductor chip on a top surface of a base substrate;

electrically interconnecting the bond pads of the semiconductor chip to the base substrate; and

removing the photoresist from the semiconductor chips.

2. The method of claim 1, wherein said singulating comprises full-cutting the wafer.